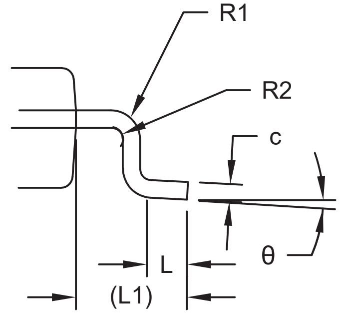
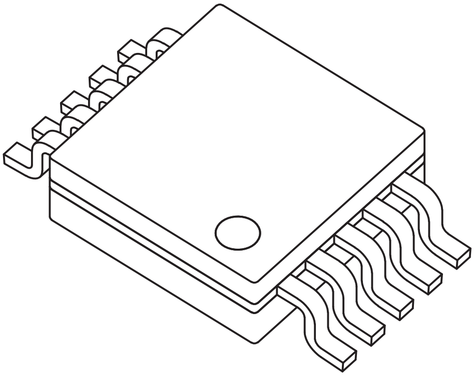
10-Lead Plastic Micro Small Outline Package (DQA)- 3x3x1.0 mm Body [MSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



SECTION A–A



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	10		
Pitch	e	0.50 BSC		
Overall Height	A	0.94	1.02	1.10
Standoff	A1	0.05	0.10	0.15
Molded Package Thickness	A2	0.91	0.92	0.95
Overall Length	D	3.00 BSC		
Molded Package Length	D1	2.23 BSC		
Overall Width	E	4.90 BSC		
Molded Package Width	E1	3.00 BSC		
Terminal Width	b	0.16	0.23	0.30
Terminal Thickness	c	0.13	0.15	0.23
Footprint	L	0.40	0.55	0.70
Terminal Length	L1	0.95 REF		
Lead Bend Radius	R1	0.08	-	-
Lead Bend Radius	R2	0.08	-	0.20
Foot Angle	θ	0°	3°	6°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.